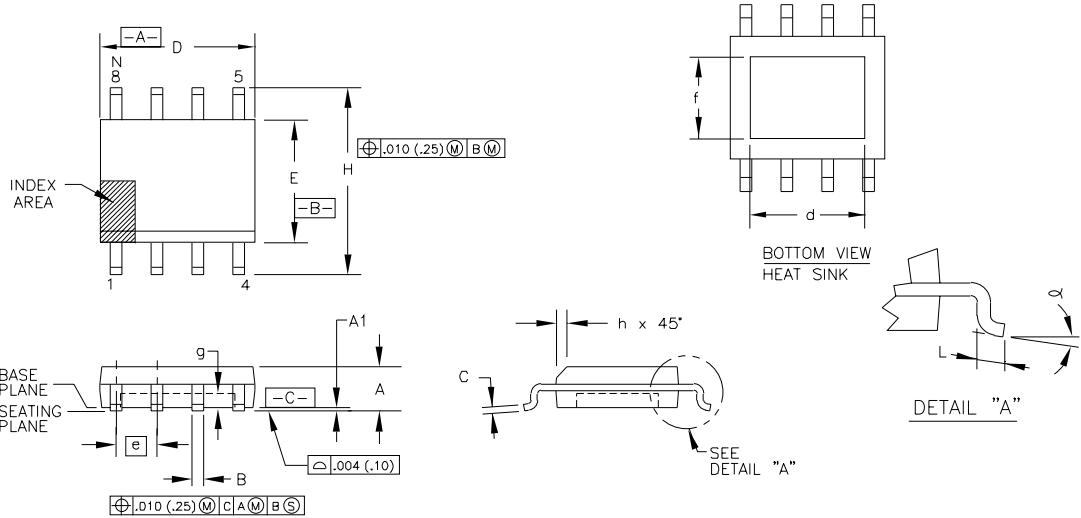


Package Number 182-1 - 8-Lead SOIC With Exposed Heat Slug



DIM	INCHES		MILLIMETERS		NOTE
	MIN.	MAX.	MIN.	MAX.	
A	.0532	.0688	1.35	1.75	
A1	.004	.0098	0.10	0.23	
B	.013	.020	0.33	0.51	7
C	.0075	.0098	0.20	0.25	
D	.189	.1968	4.80	4.98	2
d	.130	.150	3.30	3.81	9
E	.1497	.1574	3.80	4.00	3
e	.050	BASIC	1.27	BASIC	
f	.090	.110	2.29	2.79	9
g	.016	.018	0.41	0.46	9
H	.2284	.244	5.80	6.20	
h	.0099	.0196	0.25	0.50	4
L	.016	.050	0.41	1.27	5
N	8		8		6

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
2. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 IN. (0.15 mm) PER SIDE.
3. DIMENSION E DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS, INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED .010 IN. (0.25 mm) PER SIDE.
4. THE CHAMFER ON THE BODY IS OPTIONAL. IF IT IS NOT PRESENT, A VISUAL INDEX FEATURE MUST BE

LOCATED WITHIN THE CROSS-HATCHED AREA.

5. L IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE.
6. N IS THE NUMBER OF TERMINAL POSITIONS.
7. THE LEAD WIDTH B, AS MEASURED .014 IN. (0.36 mm) OR GREATER ABOVE THE SEATING PLANE, SHALL NOT EXCEED A MAXIMUM VALUE OF .024 IN. (0.61 mm).
8. LEAD TO LEAD COPLANARITY SHALL BE LESS THAN .004 IN. (0.10 mm) FROM SEATING PLANE.
9. HEAT SLUG DIMENSIONS.

PACKAGE NUMBER: ZZ182-1 REV.: A
JEDEC NUMBER: MS-012-AA

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